

- Z21 ■ Mouse bites are to be located at the 12, 3, 6, and 9 o'clock orientations.
- Z22 ■ These assemblies are ESD sensitive, ESD precautions shall be observed.
- Z23 ■ These assemblies must be clean and free from flux and all contaminants. Use of no clean flux is not acceptable.
- Z24 ■ These assemblies must comply with workmanship standards IPC-A-610 Class 2., unless otherwise specified.
- Z25 ■ Assembly: Three bumpers are to be placed where possible to provide a balanced standoff
- Z26 ■ Polygon pour along the board edge is serving as an ESD ring. Soldermask is not to be placed over the ring on either side.

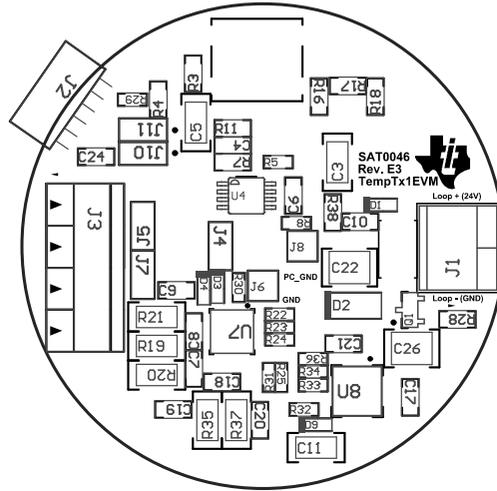


TABLE 1

Variant	Label text
001	ChangeMe!
002	ChangeMe!

COMPONENTS MARKED 'DNP' SHOULD NOT BE POPULATED.  
 ASSEMBLY VARIANT: 001

PCB VIEWED FROM TOP SIDE	BOARD #: SAT0046	REV: E4	SUN REV: Not In VersionControl
IGNORE -> Top Overlay			
PLOT NAME = Top Assembly Drawing	GENERATED : 2/5/2014	1:52:43 PM	TEXAS INSTRUMENTS



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